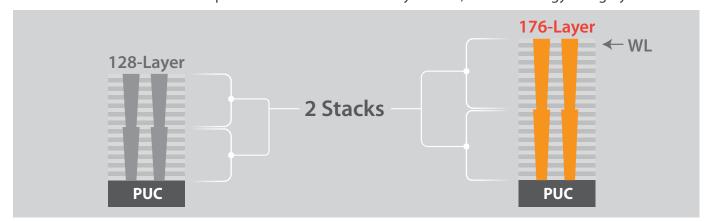
SK hynix's NAND flash lineup continues to evolve in mono-die density and available capacity configurations, supported by a proven and robust tech platform. Now we present the UD310 (UFS3.1) and UD220 (UFS2.2), high-capacity & performance mobile storage built on our latest 176-layer 4D NAND, fitted in a smaller and thinner package to meet the tight requirements of 5G smartphones.

Features

SK hynix's 176-Layer NAND Flash Inside

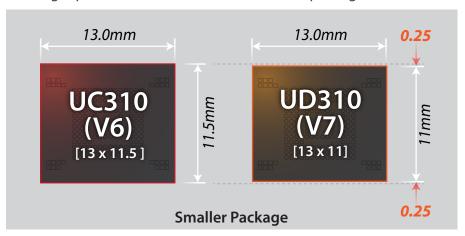
- The industry's a tallest, 176-layer NAND also utilizes the 4D NAND platform.
- · Built on the mature 4D NAND platform used since the 96-layer stack, the technology in highly reliable.



*This figure is for understanding and WLs are omitted.

Space-efficient Package Outside

- · Package shrink to 11x13mm in line with demand for smaller chips in 5G smartphones
- · Stronger performance in smaller and thinner package



_	_	→ Heigh	t		
	UC310 (V6)	UD310 (V7)			
128/256 /512GB	1.0T	0.8T			
1TB		1.0T			
Thinner Package					







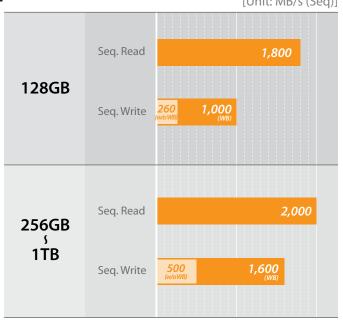
Performance

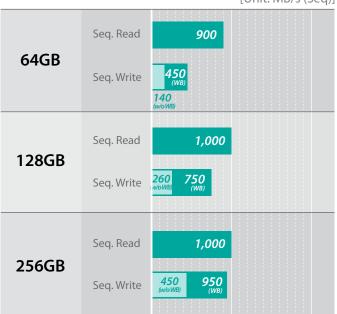
- · Stronger performance with latest 176-layer 4D NAND combined with next-gen SoC and firmware
- · Enhanced with added features for maximum user benefit advanced Write Booster (WB), Host Performance Booster (HPB) 2.0, hardware-accelerated garbage collection (HAGC)

UD310 - UFS3.1

UD220 - UFS2.2 [Unit: MB/s (Seq)]

[Unit: MB/s (Seq)]





Product Lineup

Model Name	UD310		UD220		
Density &	128GB	HN8T05DEHKX073	64GB	HN8G962EHKX037	
Part Number	256GB	HN8T15DEHKX075	128GB	HN8T062EHKX039	
	512GB	HN8T25DEHKX077	256GB	HN8T162EHKX041	
	1TB	HN8T35DZHKX079			
NAND	176-Layer 512Gb TLC		176-Layer 512Gb TLC		
PKG Size & Type	11x13x0.8T (128GB~512GB) 11x13x1.0T (1TB)		11.5x13x0.8T (64GB~256GB)		
Spec	UFS 3.1		UFS 2.2		
Voltage (vcc/vccq)	2.5V / 1.2V		3.3V / 1.8V		

Use Case



